Inventors: Wen-chou Vincent Wang et al.
Title: Structure And Material For Assembling A Low-K Si Die To
Achieve A Low Warpage And Industrial Grade Reliability Flip Chip
Package With Organic Substrate
Atty. Docket No.: ALTRP096/A1201

Sheet 1 of 1

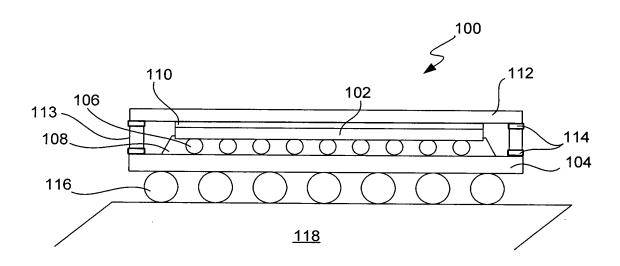


FIG. 1